


Full Material Declaration for attached parts list

Report generated: 28 November 2017, 08:46 GMT

	<p>Diotec Semiconductor AG DUNS number: 330866844 -, Kreuzmattenstr. 4, Heitersheim, B.-W., 79423, Germany Declarations authorised by: Udo Steinebrunner, Product Manager, -</p>
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Declaration effective from: 30 December 2009 [Approved on 28 November 2017, 08:43 GMT]

Materials and substances

Use/Location	Material group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Base material	Copper alloys	81.83000%	Copper	7440-50-8	100.00000%
Chip (die)	Other inorganic materials	0.09000%	Silicon dioxide	60676-86-0	1.00000%
			Gold	7440-57-5	11.50000%
			Polydimethylsiloxane rubber	63394-02-5	25.00000%
			Silicone	7440-21-3	62.50000%
Die attach	Sn-Pb solder	0.11000%	Silver	7440-22-4	2.50000%
			Tin	7440-31-5	5.00000%
			Lead	7439-92-1	92.50000%
Encapsulation	EP (Epoxy resin)	6.83000%	Silicon dioxide	60676-86-0	100.00000%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	8.61000%	Copper	7440-50-8	100.00000%
Plating	Copper plating	2.53000%	Nickel	7440-02-0	100.00000%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
KYWxx/KYZxx	Pressfit	10	g